

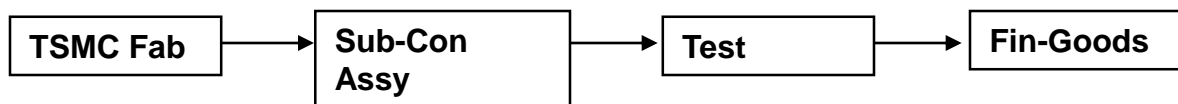
QUALIFICATION RESULTS SUMMARY OF FAB TRANSFER AT ADI PER PCN 18_0175			
TEST	SPECIFICATION	SAMPLE SIZE	RESULTS
High Temperature Operating Life (HTOL)*	JEDEC <i>JESD22-A108</i>	3*77	Passed
Highly Accelerated Stress Test (HAST)*	JEDEC <i>JESD22-A110</i>	3*77	Passed
Autoclave*	JEDEC <i>JESD22-A102</i>	3*77	Passed
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3*77	Passed
Early Life Failure (ELF)	MIL-STD-883 <i>Method 1015</i>	3*667	Passed
High Temperature Storage Life (HTSL)	JEDEC <i>JESD22-A103</i>	3*45	Passed
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	3*11	Passed
Latch-Up	JEDEC <i>JESD78</i>	3/level	Passed
Electrostatic Discharge <i>Human Body Model</i>	ESDA/JEDEC <i>JS-001</i>	3/voltage	Passed
Electrostatic Discharge <i>Field-Induced Charged Device Model</i>	JEDEC <i>JS-002</i>	3/voltage	Passed
Electrostatic Discharge <i>8KV Contact/15KV Air Discharge</i>	IEC <i>61000-4-2</i>	3/voltage	Passed

*Preconditioned per JEDEC/IPC J-STD-020



Alternate fab source for RS-232 Serial Port Driver-Receiver products. To enable additional wafer fabrication capacity

Current Flow:



Alternate Flow:

